

AMENDMENT TRANSMITTAL LETTER

Docket No.
TESSERA 3.0-236

Application No.
09/802,834

Filing Date
March 9, 2001

Examiner
W. D. Coleman

Art Unit
2823

Applicant(s): Masud Beroz and David Light

Invention: ASSEMBLIES FOR TEMPORARILY CONNECTING MICROELECTRONIC ELEMENTS
FOR TESTING AND METHODS THEREFOR

TO THE COMMISSIONER FOR PATENTS

Transmitted herewith is an amendment in the above-identified application.

The fee has been calculated and is transmitted as shown below.

CLAIMS AS AMENDED					
	Claims Remaining After Amendment	Highest Number Previously Paid	Number Extra Claims Present	Rate	
Total Claims	46	- 47 =		x	0
Independent Claims	4	- 4 =		x	0
Multiple Dependent Claims (check if applicable) <input type="checkbox"/>					0
Other fee (please specify):					0
TOTAL ADDITIONAL FEE FOR THIS AMENDMENT:					0

☒ Large Entity

☐ Small Entity

☐ No additional fee is required for this amendment.

☐ Please charge Deposit Account No. 12-1095 in the amount of \$
A duplicate copy of this sheet is enclosed.

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Michael J. Doherty

Dated: April 30, 2003

Michael J. Doherty
Attorney Reg. No.: 40,592

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I hereby certify that this correspondence is being deposited with the U.S. Postal Service with sufficient postage as First Class Mail, in an envelope addressed to: Commissioner for Patents, Washington, DC 20231, on the date shown below.

Dated: April 30, 2003

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Beroz et al

Application No.: 09/802,834

: Group Art Unit: 2823

Filed: March 9, 2001

: Examiner: W. D ^{III} Coleman

For: ASSEMBLIES FOR TEMPORARILY
CONNECTING MICROELECTRONIC
ELEMENTS FOR TESTING AND METHODS
THEREFOR

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Coleman

AMENDMENT

Commissioner for Patents
Washington, DC 20231

Dear Sir:

In response to the Office Action dated November 15, 2002, please amend the above-identified U.S. patent application as follows:

IN THE ABSTRACT

A method of making a microelectronic assembly includes providing a first microelectronic element having one or more conductive bumps, the conductive bumps including a first fusible material that transforms from a solid to a liquid at a first melting temperature, and providing a second microelectronic element having one or more conductive elements. The conductive bumps of the first microelectronic element are electrically interconnected with the conductive elements of the second

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